

# MDC\_BCW66G\_PS

# PSpice Model NPN BJT Nexperia BCW66G

# **Model Information**

Model	A macro mode	I
Call Name	MDC_BCW660	G_PS
Pin Assign	1:B 2:E 3:C	
File List	Model Library	MDC_BCW66G_PS.lib
	Model Report	MDC_BCW66G_PS.pdf

**Verified Simulator Version** 

Note

#### References

The information which was used for modeling is as follow:

[Data Sheet]
Date/Version
Product name
Company name

21 April 2017 BCW66G Nexperia

[Characteristics listed]
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Characteristics

Ic Vce Ib, hFE Ic[Vce], Vbe(sat) Ic[Temp], Vce(sat) Ic[Temp], Cc, fT Ic[Vce]

#### **Simulation Condition**

This table shows the range of evaluated simulation range that was not occurs any convergence problems in this area.

Item	Condition	Unit
Temperature	25	deg C

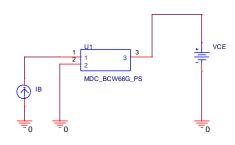


BJT	O : Implemented × : Not Implement		
Model Functions Table	RANK=1	— : Not applicable	
Functions	RANK	Implemented	
IC-VBE(Temp)	1	—	
IC-VCE-IB(Temp)	1	0	
IC-hFE(Temp)	1	0	
VCE(sat)-IC	1	0	
VBE(sat)-IC	1	0	
Сс	1	0	
Се	1	—	
fT-IC	1	0	

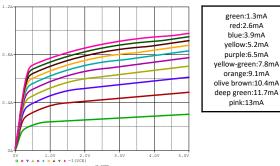


Simulation results are following. Explanatory notes — : simulated

#### Ic Vce Ib Testbench

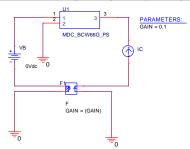


#### IcVbe[Temp] Data Sheet

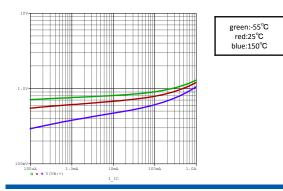


#### Vbe(sat)lc[Temp] Testbench

CONDITIONS	MIN.	TYP.	MAX.	UNIT
lc = 100 mA,lb =10 mA,note1	-	-	1.25	V
lc = 500 mA,Ib = 50 mA,note1	-	-	1.25	V

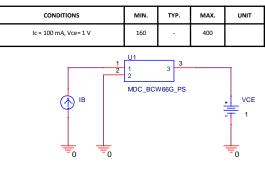


## Vbe(sat)Ic[Temp] Data Sheet

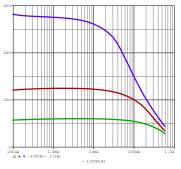


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#### hFEIc[Temp] Testbench



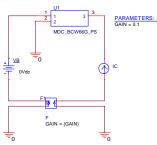
### hFElc[Temp] Data sheet



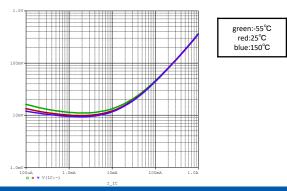


# Vce(sat)Ic[Temp] Testbench

CONDITIONS	MIN.	TYP.	MAX.	UNIT
lc = 100 mA,lb = 10 mA,note1	-	-	350	mV
Ic = 500 mA,Ib = 50 mA,note1	-	-	450	mV



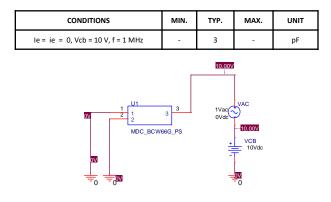
## Vce(sat)lc[Temp] Data Sheet



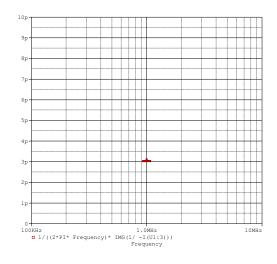


#### Simulation results are following. Explanatory notes — : simulated

#### Cc Testbench

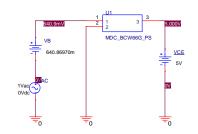


#### Cc Data Sheet

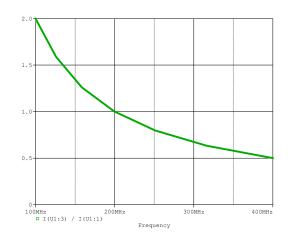


#### fTIc[Vce] Testbench

CONDITIONS	MIN.	ТҮР.	MAX.	UNIT
Vce = 5 V; Ic =10 mA; f = 100 MHz	100	-	-	MHz



## fTIc[Vce] Data Sheet





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